250V N-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY V(BR)DSS=250V; RDS(ON)=8.5Ω; ID=230mA

DESCRIPTION

This 250V enhancement mode N-channel MOSFET provides users with a competitive specification offering efficient power handling capability, high impedance and is free from thermal runaway and thermally induced secondary breakdown. Applications benefiting from this device include a variety of Telecom and general high voltage circuits.

SOT89 and SOT223 versions are also available.

FEATURES

- High voltage
- Low on-resistance
- Fast switching speed
- Low gate drive
- Low threshold
- Complementary P-channel Type ZVP4525E6
- SOT23-6 package

APPLICATIONS

- Earth Recall and dialling switches
- Electronic hook switches
- High Voltage Power MOSFET Drivers
- Telecom call routers
- Solid state relays

ORDERING INFORMATION

DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZVN4525E6TA	7	8mm embossed	3000 units
ZVN4525E6TC	13	8mm embossed	10000 units

DEVICE MARKING

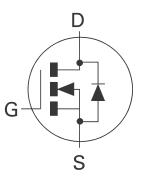
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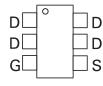


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Top View

ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DSS}	250	V
Gate Source Voltage	V _{GS}	±40	V
Continuous Drain Current (V _{GS} =10V; TA=25°C)(a) (V _{GS} =10V; TA=70°C)(a)	I _D I _D	230 183	mA mA
Pulsed Drain Current (c)	I _{DM}	1.44	A
Continuous Source Current (Body Diode)	I _S	1.1	А
Pulsed Source Current (Body Diode)	I _{SM}	1.44	А
Power Dissipation at T _A =25°C (a) Linear Derating Factor	P _D	1.1 8.8	W mW/°C
Operating and Storage Temperature Range	T _j :T _{stg}	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{ extsf{ heta}JA}$	113	°C/W
Junction to Ambient (b)	$R_{_{ extsf{ heta}JA}}$	65	°C/W

NOTES

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at t ${\leqslant}5$ secs.

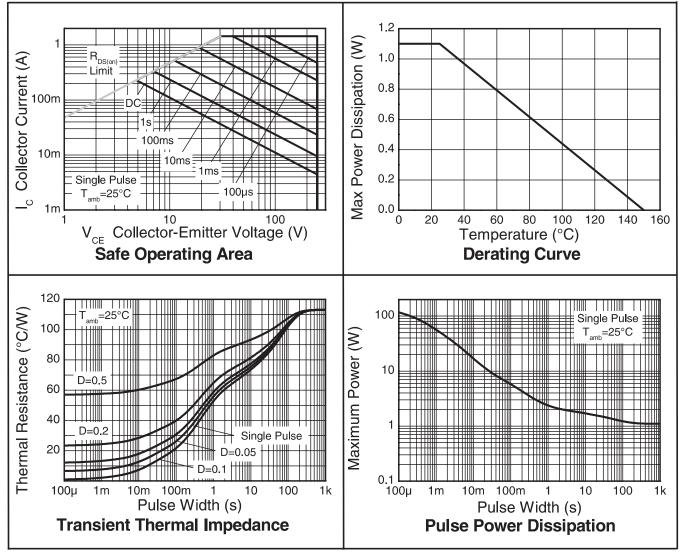
(c) Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal

NB High Voltage Applications

For high voltage applications, the appropriate industry sector guidelines should be considered with regard to voltage spacing between conductors.



CHARACTERISTICS





ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}C$ unless otherwise stated).

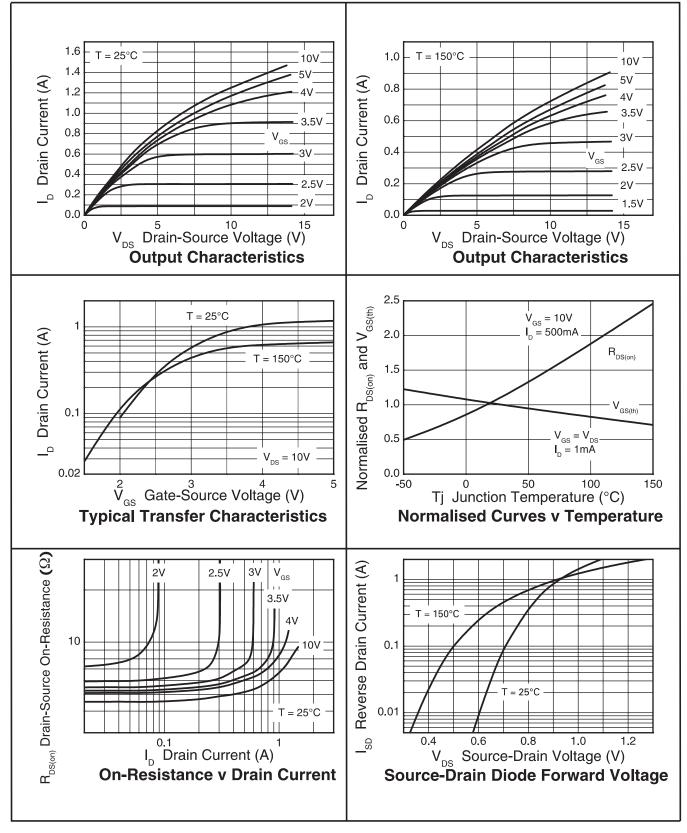
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNI T	CONDITIONS.	
STATIC	1	1	1		1		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	250	285		V	I _D =1mA, V _{GS} =0V	
Zero Gate Voltage Drain Current	I _{DSS}		35	500	nA	V _{DS} =250V, V _{GS} =0V	
Gate-Body Leakage	I _{GSS}		±1	±100	nA	$V_{GS}=\pm40V, V_{DS}=0V$	
Gate-Source Threshold Voltage	V _{GS(th)}	0.8	1.4	1.8	V	$I_{D} = 1mA, V_{DS} = V_{GS}$	
Static Drain-Source On-State Resistance (1)	R _{DS(on)}		5.6 5.9 6.4	8.5 9.0 9.5	Ω Ω Ω	V _{GS} =10V, I _D =500mA V _{GS} =4.5V, I _D =360mA V _{GS} =2.4V, I _D =20mA	
Forward Transconductance (3)	g _{fs}	0.3	0.475		S	V _{DS} =10V,I _D =0.3A	
DYNAMIC (3)						•	
Input Capacitance	C _{iss}		72		pF	V _{DS} =25 V, V _{GS} =0V, f=1MHz	
Output Capacitance	C _{oss}		11		pF		
Reverse Transfer Capacitance	C _{rss}		3.6		pF	1	
SWITCHING(2) (3)	-		_			-	
Turn-On Delay Time	t _{d(on)}		1.25		ns		
Rise Time	t,		1.70		ns	$V_{DD} = 30V, I_D = 360mA$ $R_G = 50\Omega, V_{qs} = 10V$ (refer to test circuit)	
Turn-Off Delay Time	t _{d(off)}		11.40		ns	(refer to test circuit)	
Fall Time	t _f		3.5		ns		
Total Gate Charge	Q _g		2.6	3.65	nC	V _{DS} =25V,V _{GS} =10V, I _D =360mA(refer to	
Gate-Source Charge	Q _{gs}		0.2	0.28	nC		
Gate Drain Charge	Q _{gd}		0.5	0.70	nC	test circuit)	
SOURCE-DRAIN DIODE	•		-	•	•	•	
Diode Forward Voltage (1)	V _{SD}			0.97	V	T _j =25°C, I _S =360mA, V _{GS} =0V	
Reverse Recovery Time (3)	t _{rr}		186	260	ns	$T_{i}=25^{\circ}C, I_{F}=360mA,$	
Reverse Recovery Charge (3)	Q _{rr}		34	48	nC	di/dt= 100A/µs	

(2) Switching characteristics are independent of operating junction temperature.

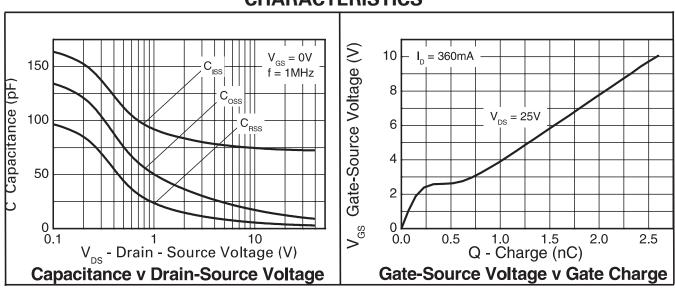
(3) For design aid only, not subject to production testing.



TYPICAL CHARACTERISTICS

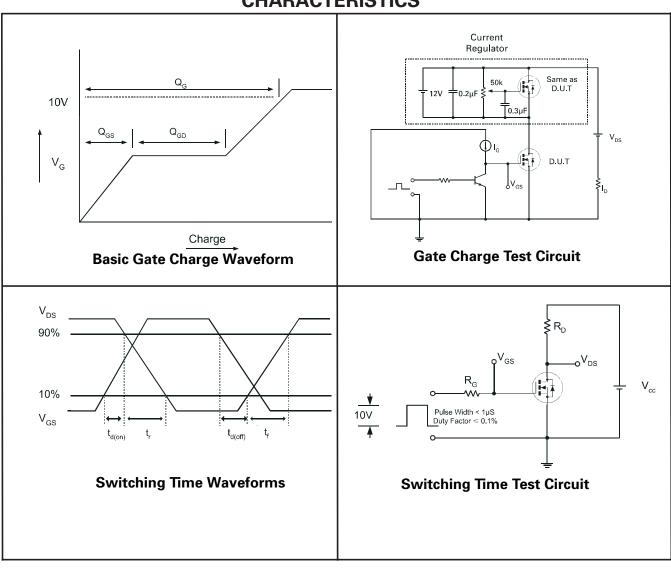






CHARACTERISTICS

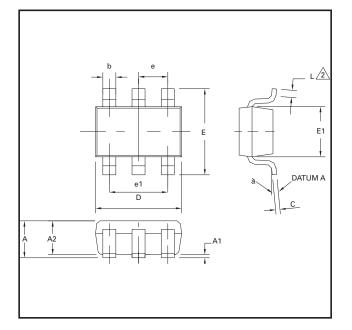




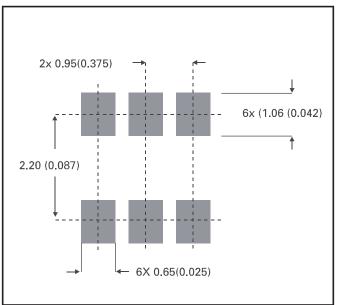
CHARACTERISTICS



PACKAGE DIMENSIONS



PAD LAYOUT DETAILS



DIM	Millimetres		Inches		
	Min	Max	Min	Max	
А	0.90	1.45	0.35	0.057	
A1	0.00	0.15	0	0.006	
A2	0.90	1.30	0.035	0.051	
b	0.35	0.50	0.014	0.019	
С	0.09	0.20	0.0035	0.008	
D	2.80	3.00	0.110	0.118	
E	2.60	3.00	0.102	0.118	
E1	1.50	1.75	0.059	0.069	
L	0.10	0.60	0.004	0.002	
е	0.95 REF		0.037 REF		
e1	1.90 REF		0.074 REF		
L	0°	10°	0°	10°	

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